A Look Back on 2018

This year, we continued our global flexible electronics expansion of the FLEX conference in China and Taiwan. In addition, we welcomed the Electronic System Design Alliance (ESDA) as the fourth SEMI strategic association partner, connecting yet another fundamental link in the electronics supply chain.

The year of 2018 has been a year of gaining momentum in the development and maturation of the flexible hybrid electronics (FHE) ecosystem with the continued R&D investment in FlexTech and the launch of the next phase of NBMC (Nano-Bio Materials Consortium). With our partners in Army Research Laboratories, we issued an RFP mid-year that resulted in three new projects at a combined federal and industry investment of over $4 million. Out of numerous submissions of exceptional quality, the project topics selected included development of a self-powered sensor platform, a flexible FOWLP integrated circuit for high density electromyography, and 3D packaging technology development for FHE. R&D teams include principal investigators from the University of Texas at El Paso, the University of California Los Angeles, I3 Electronics, ITN Energy Systems, Molex, ENrG, Sunray Scientific, and the University of Rhode Island.

Building upon the foundational innovation of the last 5 years, the next phase of NBMC has launched in partnership with the Air Force Research Laboratories. This approximate 6 year initiative will drive the human performance and augmentation technologies to the next phase of medical relevancy matching US Air Force missions in En Route Care and Aeromed to industry priorities such as point of care diagnostics and telemed.

Before we close out the year, we look forward to a refreshed SEMI website and improved customers’ experience with ready access to news, events, and technology community topics. And of course, our premier industry event, FLEX 2019, is in the planning stages and set for February 18-21, 2019 at the Hyatt Regency, Monterey, CA. Be sure to join us, learn about the leading edge development, hear from industry leaders, and become part of the exciting collaboration in 2019.

From all of us at SEMI-FlexTech, we hope you have a safe and joyful holiday season. Thank you for all your hard work and contribution in the advancement of flexible electronics and we look forward to working with you in 2019.

With our best wishes,

Dr. Melissa Grupen-Shemansky
Executive Director & CTO

Project Updates

FALL PROJECTS CLOSE OUT

This Fall brought two programs to a close:

- “Ultra Thin, Flexible Integrated Power Pack for Functional Electronic Printed (FEP) Devices” by ITN with partners Lucintech and ENrG
- “Highly Flexible Audio Enabled Smart Tag” by PARC
News and Announcements

**SEMI Wins Award for Nano-Bio Materials Consortium to Grow Digital Health Industry.**

SEMI announced that it has signed a new agreement with the U.S. Air Force Research Laboratory (AFRL) to expand the Nano-Bio Materials Consortium’s (NBMC) work in advancing human monitoring technology innovations for telemedicine and digital health. The program is designed to include $20 million in direct federal funding and $41 million overall in the next six years with additional contributions from state and industry sources. The grant guarantees $7 million of government funds for the first year’s launch of the renewed program.
Don't Wait! Register for FLEX Before Early Bird Registration Ends

Whether it's an all-in combo pass or just for FLEX, secure your spot for the 18th annual Flexible and Printed Electronics Conference and Exhibition on February 18-21, 2019 in Monterey, California.

Early bird registration for FLEX 2019 ends on December 15. Save some money and register before you leave for the holidays. Also remember to reserve your hotel room for quick access to the conference center.

FlexTech Taiwan Committee Launched to Advance Flexible Hybrid Electronics

SEMI Taiwan today announced the formation of the FlexTech Taiwan Steering Committee. Serving as a platform that connects industry, academia, research and government, the committee will focus on identifying market trends and needs, solving technical challenges and accelerating innovation and business development to advance the flexible hybrid electronics industry and open business opportunities for its members.

Key focus areas of the FlexTech Taiwan Steering Committee will include:

- Capitalizing on Taiwan’s success in semiconductor and LCD/LED displays to build a complete flexible hybrid electronics ecosystem
- Advocating for government policies on developing emerging industries, technology research funding, and talent development
- Organizing exhibitions and other events to raise awareness and communicate the value of flexible hybrid electronics the electronics industry
- Establishing industry standards to accelerate research and development and facilitate technology and product development

Technology Communities News

MSIG

- Attend Fraunhofer IPMS’ MEMS Industry Partner Day at our Milpitas HQ on February 8, 2019.

Upcoming Events

**CES 2019**
SMART STARTS HERE - SEMI Pavilion
Booth #40731
Las Vegas, Nevada, USA
JANUARY 8-11, 2019

See yourself at CES!

**FLEX 2019**
Monterey, California, USA
FEBRUARY 18-21, 2019

Register & Save